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March 2015

FDD6612A/FDU6612A

30V N-Channel PowerTrench^ò MOSFET

General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $R_{\text{DS}(\text{ON})}$, fast switching speed and extremely low $R_{\text{DS}(\text{ON})}$ in a small package.

Applications

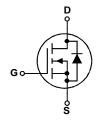
- DC/DC converter
- Motor Drives

Features

- 30 A, 30 V $R_{DS(ON)} = 20 \text{ m}\Omega \text{ @ V}_{GS} = 10 \text{ V}$ $R_{DS(ON)} = 28 \text{ m}\Omega \text{ @ V}_{GS} = 4.5 \text{ V}$
- · Low gate charge
- · Fast Switching
- High performance trench technology for extremely low $R_{\mbox{\scriptsize DS(ON)}}$







Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parai	meter		Ratings	Units
V_{DSS}	Drain-Source Voltage			30	V
V _{GSS}	Gate-Source Voltage			±20	V
I _D	Continuous Drain Current	@T _C =25°C	(Note 3)	30	Α
		@T _A =25°C	(Note 1a)	9.5	
		Pulsed	(Note 1a)	60	
P _D	Power Dissipation	@T _C =25°C	(Note 1)	36	W
		@T _A =25°C	(Note 1a)	2.8	
		@T _A =25°C	(Note 1b)	1.3	
T_J , T_{STG}	Operating and Storage Junction Temperature Range		−55 to +175	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	3.9	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	45	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1b)	96	°C/W

Package Marking and Ordering Information

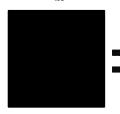
Device Marking	Device	Package	Reel Size	Tape width	Quantity
FDD6612A	FDD6612A	D-PAK (TO-252)	13"	16mm	2500 units
FDU6612A	FDU6612A	I-PAK (TO-251)	Tube	N/A	75

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-So	ource Avalanche Ratings (Not	e 2)		I	I	I
W _{DSS}	Drain-Source Avalanche Energy	Single Pulse, V _{DD} = 27 V, I _D =10 A			51	mJ
I _{AR}	Drain-Source Avalanche Current				10	Α
Off Char	acteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	30			V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A,Referenced to 25°C		25		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2.0	3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I _D = 250 μA,Referenced to 25°C		- 5.1		mV/°C
R _{DS(on)}	Static Drain–Source On–Resistance			15 20 23	20 28 33	mΩ
g FS	Forward Transconductance	$V_{DS} = 5 \text{ V}, \qquad I_{D} = 9.5 \text{ A}$		28		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance			660		pF
Coss	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$		170		pF
C _{rss}	Reverse Transfer Capacitance	f = 1.0 MHz		90		pF
R _G	Gate Resistance	V _{GS} = 15 Mv, f = 1.0 MHz		2.3		Ω
Switchin	ng Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time			9	18	ns
t _r	Turn-On Rise Time	$V_{DD} = 15 \text{ V}, I_{D} = 1 \text{ A},$		5	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		24	38	ns
t _f	Turn-Off Fall Time			4	8	ns
Q_g	Total Gate Charge			6.7	9.4	nC
Q_{gs}	Gate-Source Charge	$V_{DS} = 15 \text{ V}, \qquad I_{D} = 9.5 \text{ A},$ $V_{GS} = 5 \text{ V}$		2.1		nC
Q_{qd}	Gate-Drain Charge	, vos - 0 v		2.7		nC

Electric	cal Characteristics	T _A = 25°C unless otherwise noted				
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-S	ource Diode Characteristics	and Maximum Ratings	1			
Is	Maximum Continuous Drain-Sourc	e Diode Forward Current			2.3	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.3 \text{ A}$ (Note 2)		0.8	1.2	V
trr	Diode Reverse Recovery Time	IF = 9.5 A, diF/dt = 100 A/µs		20		nS
Qrr	Diode Reverse Recovery Charge			10		nC

Notes

1. R_{8JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{8JC} is guaranteed by design while R_{8CA} is determined by the user's board design.



a) $R_{\theta JA} = 45$ °C/W when mounted on a 1in^2 pad of 2 oz copper



b) $R_{\theta JA} = 96^{\circ}C/W$ when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

3. Maximum current is calculated as: $\sqrt{\frac{P_{\text{D}}}{R_{\text{DS(ON)}}}}$

where P_D is maximum power dissipation at T_C = 25°C and $R_{DS(cn)}$ is at $T_{J(max)}$ and V_{GS} = 10V. Package current limitation is 21A

Typical Characteristics

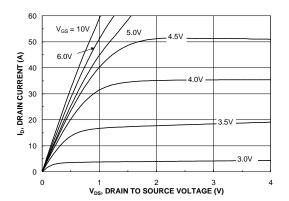


Figure 1. On-Region Characteristics

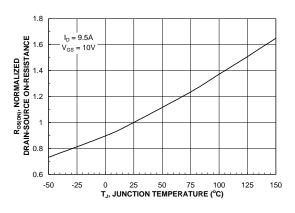


Figure 3. On-Resistance Variation withTemperature

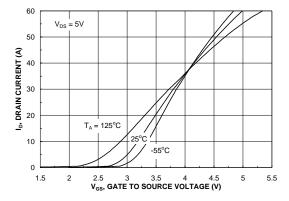


Figure 5. Transfer Characteristics

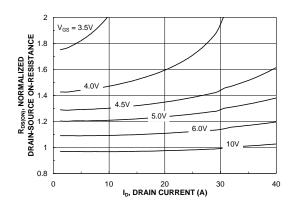


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

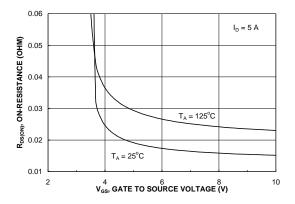


Figure 4. On-Resistance Variation with Gate-to-Source Voltage

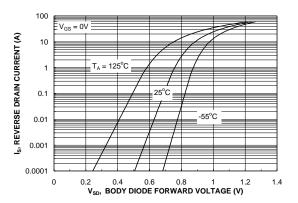
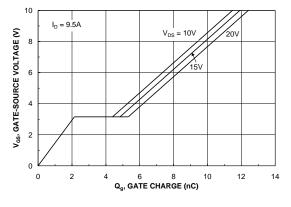


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Characteristics



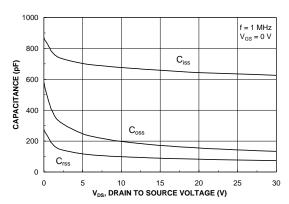
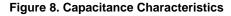
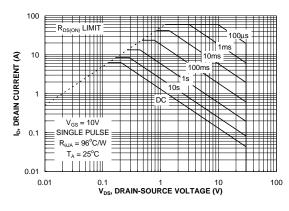


Figure 7. Gate Charge Characteristics





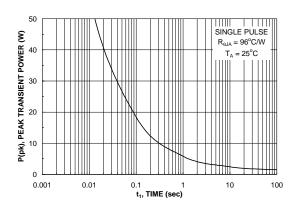


Figure 9. Maximum Safe Operating Area

Figure 10. Single Pulse Maximum Power Dissipation

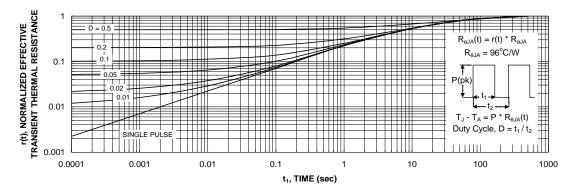
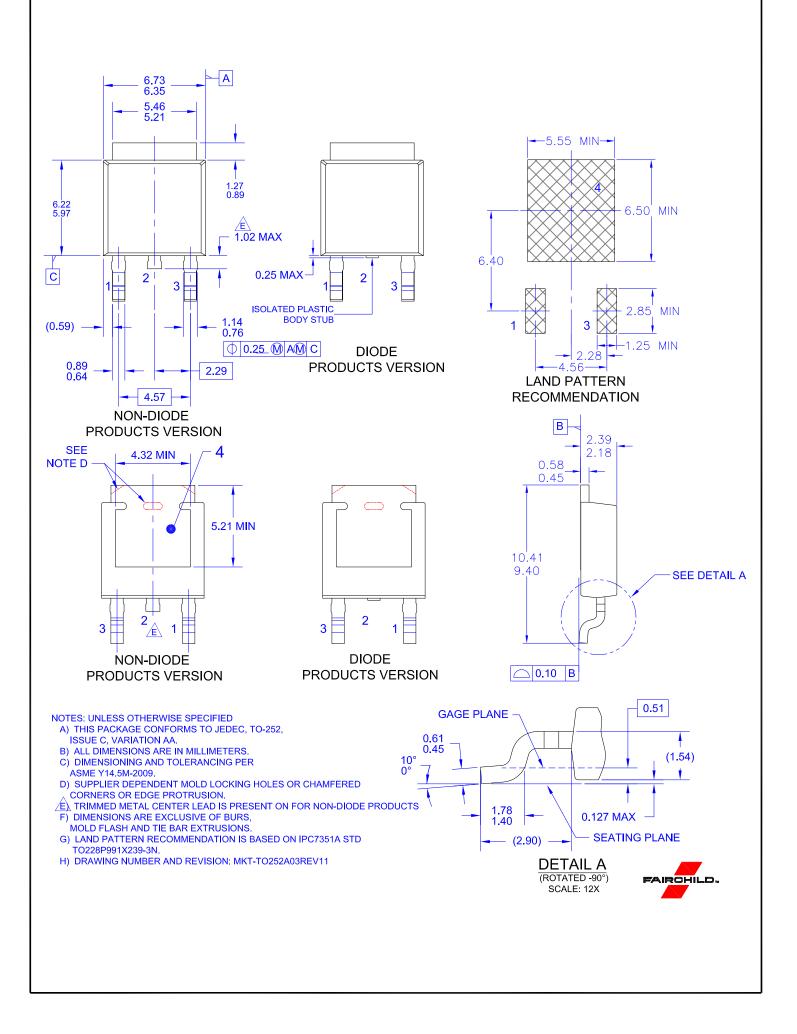


Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.



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